

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Mou-Shiung Lin	10/19/2007
Jin-Yuan Lee	10/20/2007
RECEIVING PARTY DATA	
Name:	MEGICA CORPORATION
Street Address:	Room 301/302, No. 47, Park 2nd Rd.,
City:	Hsinchu
State/Country:	TAIWAN
Postal Code:	300
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11856075
CORRESPONDENCE DATA	
Fax Number:	(617)910-8363
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	+886-3-5783398
Email:	marsyang@megica.com.tw
Correspondent Name:	MEGICA CORPORATION
Address Line 1:	Room 301/302, No. 47, Park 2nd Rd.,
Address Line 4:	Hsinchu, TAIWAN 300
ATTORNEY DOCKET NUMBER:	MEG00-005D-E13
NAME OF SUBMITTER:	Mou-Shiung Lin
Total Attachments: 2 source=MEG00-005D-E13-assignment#page1.tif source=MEG00-005D-E13-assignment#page2.tif	

OP \$40.00 11856075

ASSIGNMENT

WHEREAS,

1. Mou-Shiung Lin

2. Jin-Yuan Lee

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **POST PASSIVATION INTERCONNECTION SCHEMES ON TOP OF IC CHIP**

Filed: 9/17/2007

Serial No. 11/856,075

Executed concurrently with the execution of this instrument

WHEREAS, Megica Corporation

of Room 301/302, No 47, Park 2nd Rd., Science-Based Industrial Park Hsinchu,
Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Mou-Shiung Lin

Date: Oct. 19, 2007

Sole or First Joint Inventor: Mou-Shiung Lin

Signature: Jin-Yuan Lee

Date: 2007 Oct 20

Second Joint Inventor: Jin-Yuan Lee